

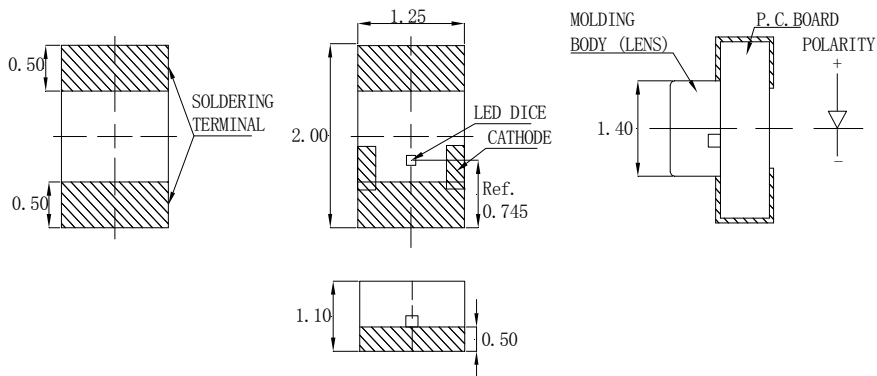
Features

- 2.0mm*1.25mm SMT LED, Super thin (1.10H mm)
- Low Power Consumption
- Wide Viewing Angle
- Various Colors
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow and wave solder process.
- Meet ROHS Green Products
- Package: 3000pcs/Reel

Applications

- Backlight and Indicator

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.2\text{mm}$ (.0079") unless otherwise noted.
3. Specifications are subject to change without notice



Selection Guide

Part No	Lens Type	Dice	Emitted Color
FSL-20125110PG-TC3	Water Clear	GaN	Green

Electrical / Optical Characteristics At Ta=25°C

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Condition
Iv	Luminous Intensity	250	300		mcd	IF=20mA
2θ1/2	Viewing Angle		130		deg	IF=20mA
λ Peak	Peak Emission Wavelength		525		nm	IF=20mA
λ d	Dominant Wavelength		530		nm	IF=20mA
Δλ	Spectral Line Half-Width		35		nm	IF=20mA
VF	Forward Voltage		3.4	3.8	V	IF=20mA
IR	Reverse Current			10	μ A	VR 5V

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 optical centerline value

Absolute Maximum Ratings At Ta=25°C

Parameter	Green	Unit
Power Dissipation	120	mW
Peak Forward Current[1]	100	mA
Continuous Forward Current	30	mA
Dreading Linear From 30°C	0.5	mA/°C
Reverse Voltage	5	V
Operating Temperature Range	-20°C to + 80°C	
Storage Temperature Range	-30°C to + 100°C	
Soldering Condition	260°C For 5 Seconds	

Note:

1. 1/10DutyCycle, 0.1msPulseWidth

Electrical Optical Characteristics Curves At Ta=25°C

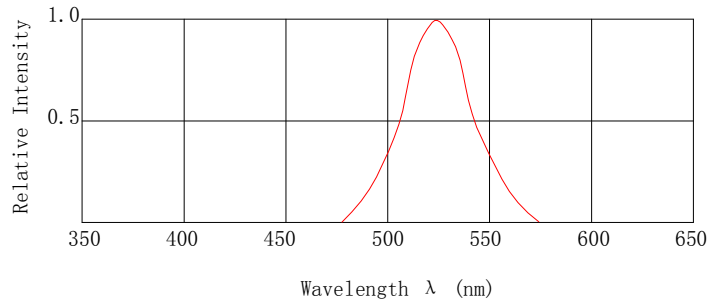


Fig.1 Relative Intensity vs. Wavelength

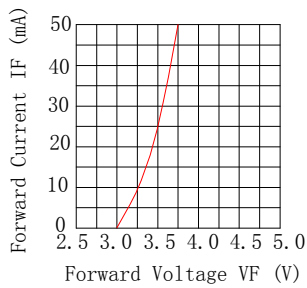


Fig.2 Forward Current VS. Forward Voltage

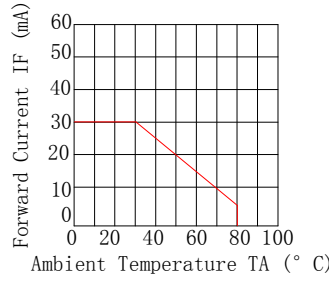


Fig.3 Forward Current Derating Curve

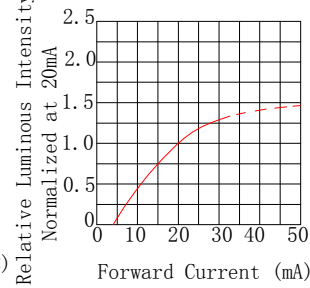


Fig.4 Relative Luminous Intensity VS. Forward Current

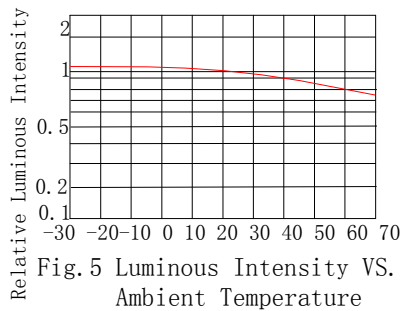


Fig.5 Luminous Intensity VS. Ambient Temperature

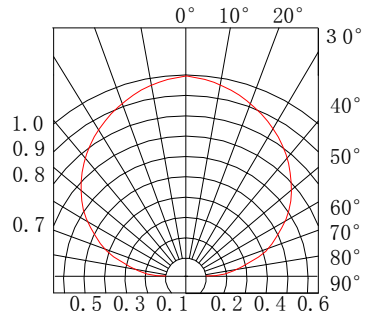
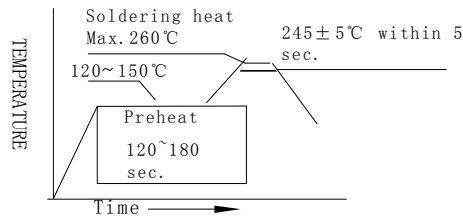


Fig.6 Spatial Distribution

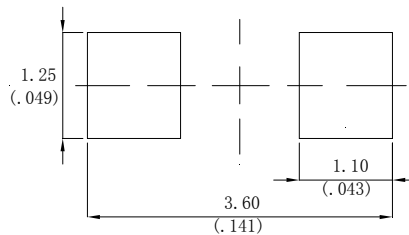
SMT Reflow Soldering Instructions



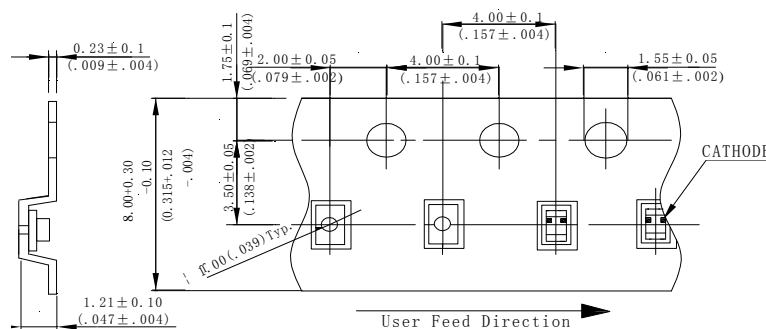
Notes:

1. Sells gives no other assurances regarding the ability of to withstand ESD. It is recommended to use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.
2. Reflow soldering should not be done more than two times.
3. Do not stress LED when soldering, and do not warp the circuit board after soldering
4. While using Iron, Power dissipation of Iron should be smaller than 25W, and temperature should be controllable. The work should be finished within 2 sec under 320°C for once only.

Recommended Soldering Pad Dimensions



Package Specifications (Units: mm (inches))



Notes:

1. The LEDs should be used within a year.
2. The LEDs should be kept in 5~30°C and 60% RH for less.
3. The LEDs should be used within 24 hours, or else should be kept a 5~30°C and 30% RH or less. And LEDs should be used within 7 days after opening the package.